Features

- ESD/Surge Protection for 1 Line with Unidirectional.
- Provide ESD protection for each line to **IEC 61000-4-2 (ESD) ±30kV (air / contact)** **IEC 61000-4-5 (Lightning) 18A (8/20μs)**
- For operating voltage of **20V and below**
- **1.6mm x 1.0mm DFN package** saves board space
- Protect one I/O line or one power line
- Fast turn-on and Low clamping voltage
- Solid-state silicon-avalanche and active circuit triggering technology
- *Green Part*
- *AEC-Q101 qualified*

Applications

- Automotive
- Power Supply Protection
- USB VBUS Protection
- Cellular Handsets and Accessories
- Small Panel Modules
- Portable Devices
- Touch Panels
- Notebooks and Handhelds
- Peripherals

Description

AZ9720-01F is a design which includes a unidirectional surge rated clamping cell to protect one power line, or one control line, or one low speed data line in an electronic systems. The AZ9720-01F has been specifically designed to protect sensitive components which are connected to power and control lines from over-voltage damage and latch-up caused by Electrostatic Discharging (ESD), Lightning, and Cable Discharge Event (CDE).

AZ9720-01F is a unique design which includes proprietary clamping cell in a single package. During transient conditions, the proprietary clamping cell prevents over-voltage on the power line or control/data lines, protecting any downstream components.

AZ9720-01F may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (±15kV air, ±8kV contact discharge).

Circuit Diagram / Pin Configuration

DFN1610P2E (Bottom View)
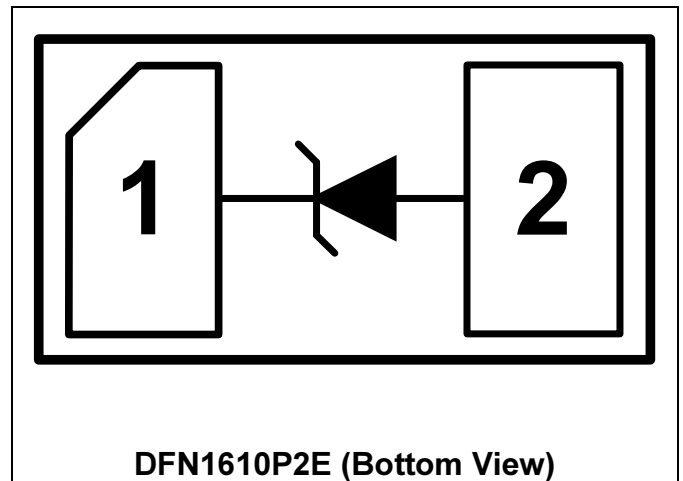
SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS			
PARAMETER	SYMBOL	RATING	UNITS
Peak Pulse Current (tp =8/20μs)	I_{PP}	18	A
Operating Supply Voltage (pin-1 to pin-2)	V_{DC}	22	V
pin-1 to pin-2 ESD per IEC 61000-4-2 (Air)	V_{ESD-1}	±30	kV
pin-1 to pin-2 ESD per IEC 61000-4-2 (Contact)	V_{ESD-2}	±30	kV
Lead Soldering Temperature	T_{SOL}	260 (10 sec.)	^{o}C
Operating Temperature	T_{OP}	-55 to +125	^{o}C
Storage Temperature	T_{STO}	-55 to +150	^{o}C

ELECTRICAL CHARACTERISTICS						
PARAMETER	SYMBOL	CONDITIONS	MINI	TYP	MAX	UNITS
Reverse Stand-Off Voltage	V_{RWM}	pin-1 to pin-2, T=25 ^{o}C			20	V
Reverse Leakage Current	I_{Leak}	V_{RWM} = 20V, T=25 ^{o}C, pin-1 to pin-2			0.1	μA
Reverse Breakdown Voltage	V_{BV}	I_{BV} = 1mA, T=25 ^{o}C, pin-1 to pin-2	22.8		27	V
Forward Voltage	V_{F}	I_{F} = 15mA, T=25 ^{o}C, pin-2 to pin-1	0.5		1.2	V
Surge Clamping Voltage	$V_{CL-surge}$	I_{PP}=5A, tp=8/20μs, T=25 ^{o}C, pin-1 to pin-2		24.5		V
		I_{PP}=18A, tp=8/20μs, T=25 ^{o}C, pin-1 to pin-2		28		V
ESD Clamping Voltage (Note 1)	V_{clamp}	IEC 61000-4-2 +8kV (I_{TLP} = 16A), T=25 ^{o}C, Contact mode, pin-1 to pin-2		25.5		V
ESD Dynamic Turn-on Resistance	$R_{dynamic}$	IEC 61000-4-2 0~+8kV, T=25 ^{o}C, Contact mode, pin-1 to pin-2		0.06		Ω
Channel Input Capacitance	C_{IN}	V_{R} = 0V, f = 1MHz, T=25 ^{o}C, pin-1 to pin-2		250	300	pF

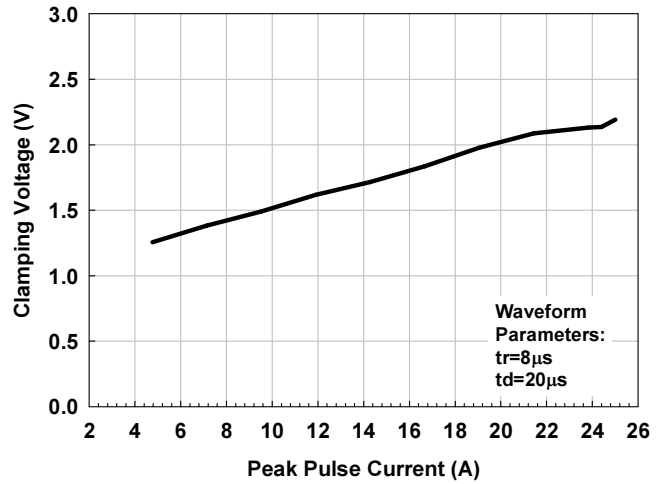Note 1: ESD Clamping Voltage was measured by Transmission Line Pulsing (TLP) System.
TLP conditions: Z_{0}= 50Ω, t_{p}= 100ns, t_{r}= 1ns.

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Typical Characteristics

Reverse Clamping Voltage vs. Peak Pulse Current

Clamping Voltage (V) vs. Peak Pulse Current (A)

Waveform
Parameters:
tr=8μs
td=20μs
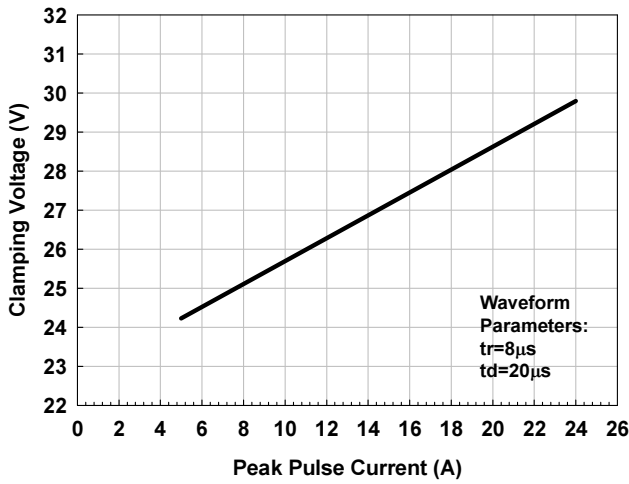
Forward Clamping Voltage vs. Peak Pulse Current

Clamping Voltage (V) vs. Peak Pulse Current (A)

Waveform
Parameters:
tr=8μs
td=20μs

Transmission Line Pulsing (TLP) Measurement

Transmission Line Pulsing (TLP) Current (A) vs. Transmission Line Pulsing (TLP) Voltage (V)

V_pulse
Pulse from a
transmission line
100ns
TLP_I
TLP_V
DUT

Input Capacitance (pF) vs. Input Voltage (V)

f = 1MHz, T = 25°C
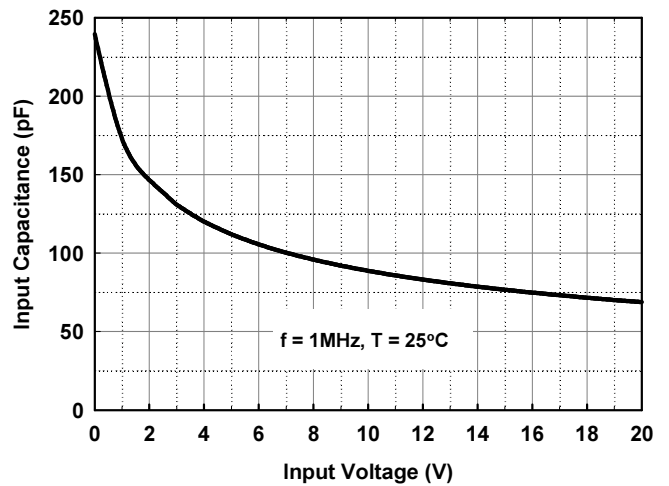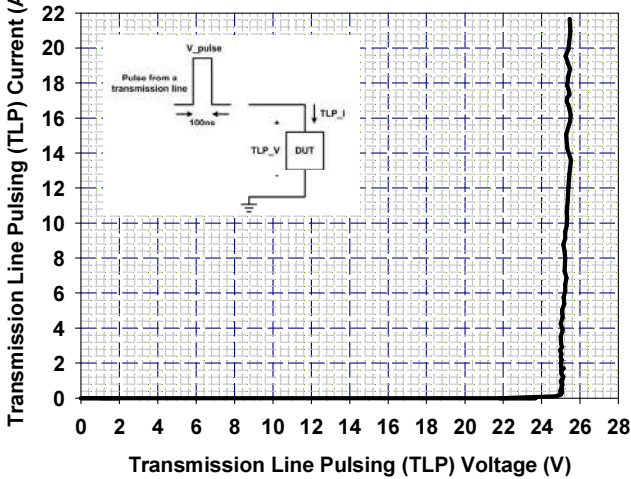
Applications Information

The AZ9720-01F is designed to protect one line against System ESD/Lightning pulses by clamping them to an acceptable reference.

The usage of the AZ9720-01F is shown in Fig. 1. Protected lines, such as data lines, control lines, or power lines, are connected at pin 1. The pin 2 should be connected directly to a ground plane on the board. All path lengths connected to the pins of AZ9720-01F should be kept as short as possible to minimize parasitic inductance in the board traces.

In order to obtain enough suppression of ESD induced transient, good circuit board is critical. Thus, the following guidelines are recommended:

● Minimize the path length between the protected lines and the AZ9720-01F.

● Place the AZ9720-01F near the input terminals or connectors to restrict transient coupling.

● The ESD current return path to ground should be kept as short as possible.

● Use ground planes whenever possible.

● NEVER route critical signals near board edges and near the lines which the ESD transient easily injects to.
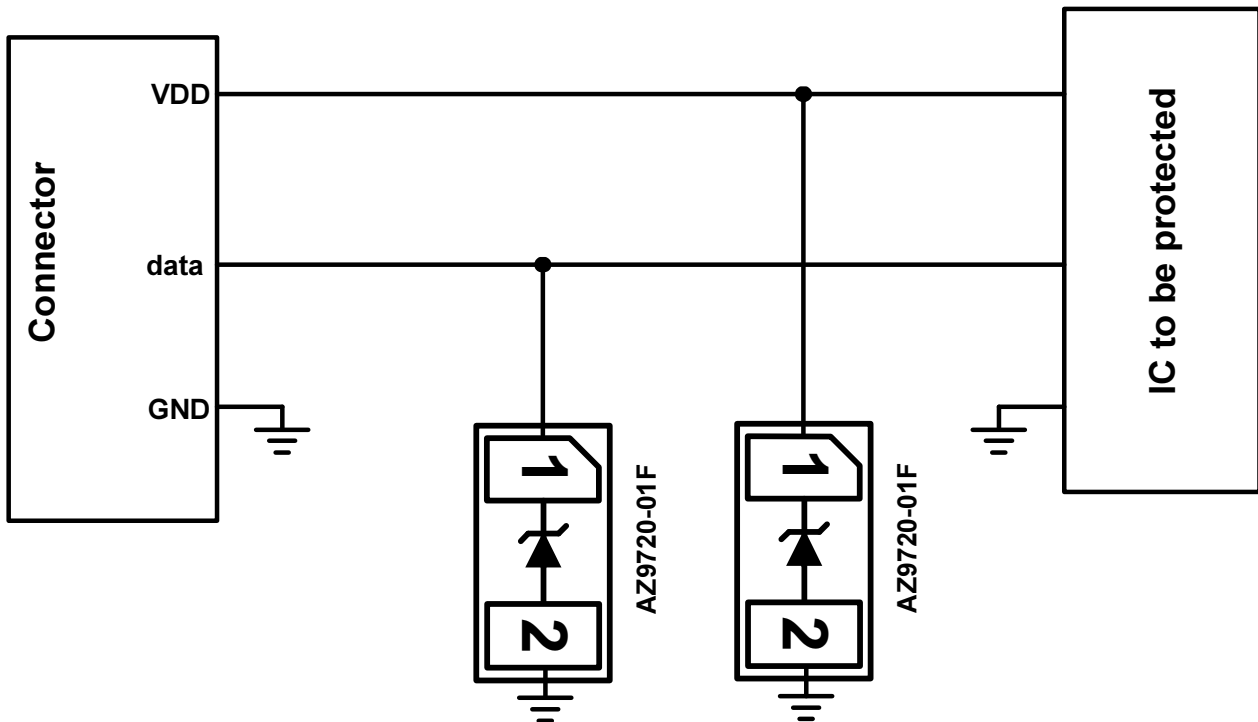

Fig. 1

Fig. 2 shows another simplified example of using AZ9720-01F to protect the control lines, low speed data lines, and power lines from ESD transient stress.
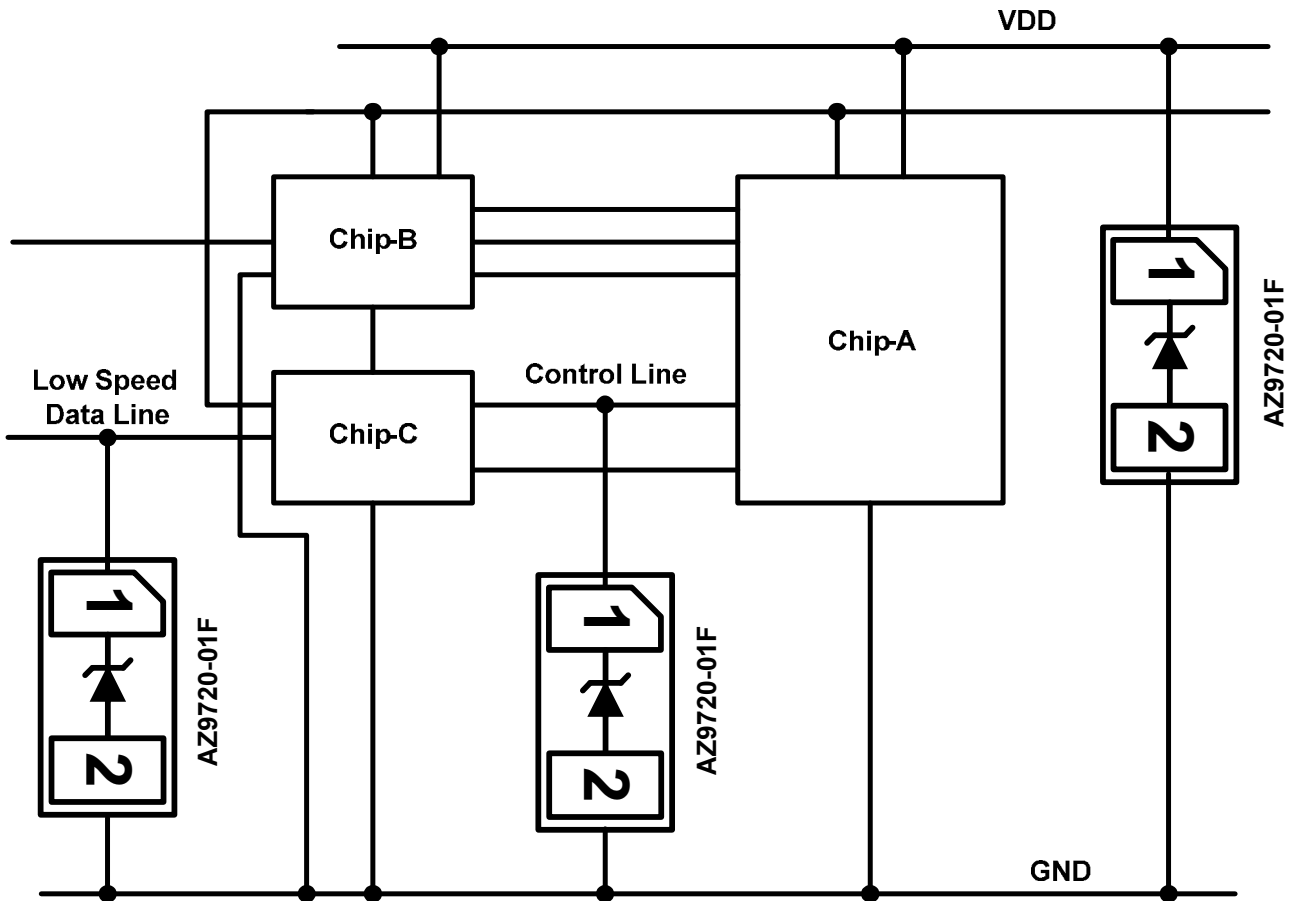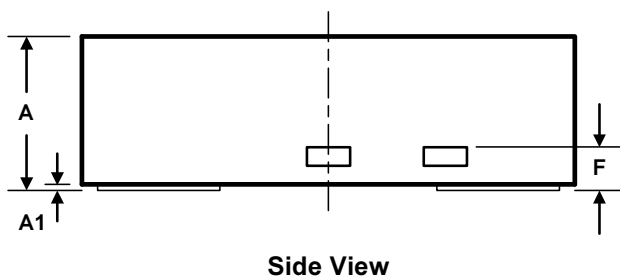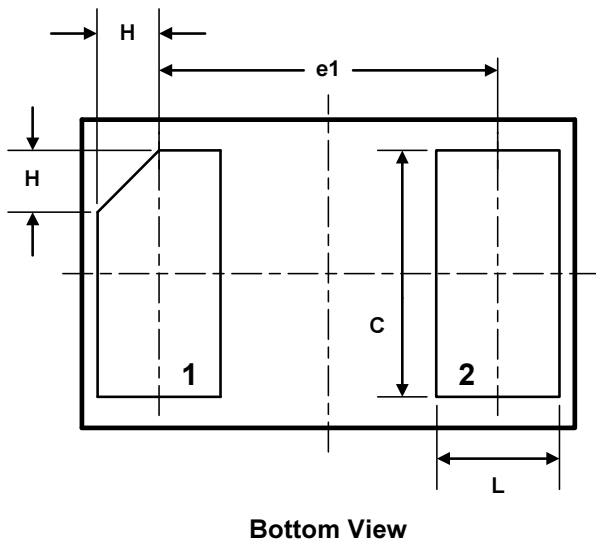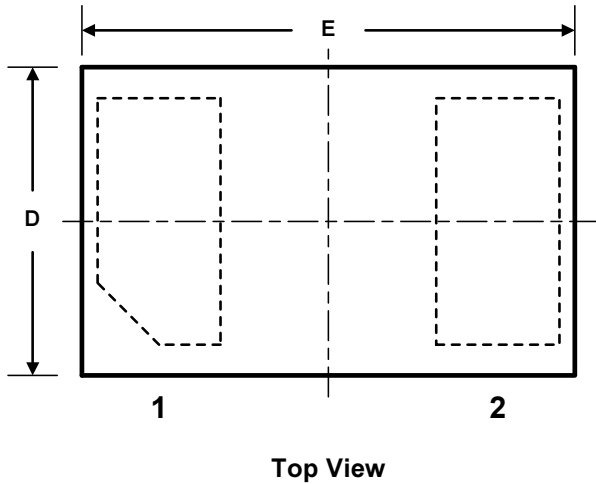

Fig. 2

Mechanical Details

DFN1610P2E PACKAGE DIAGRAMS

Top View

Bottom View

Side View

PACKAGE DIMENSIONS

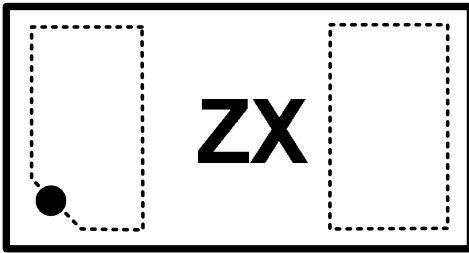| SYMBOL	Millimeter		
	Min.	Typ.	Max.
D	0.95	1.00	1.05
E	1.55	1.60	1.65
C	0.75	0.80	0.85
A	0.45	0.50	0.55
A1	-	0.02	0.05
e1	1.10BSC		
F	0.10	0.15	0.20
H	0.15	0.20	0.25
L	0.35	0.40	0.45

LAND LAYOUT

Unit: mm
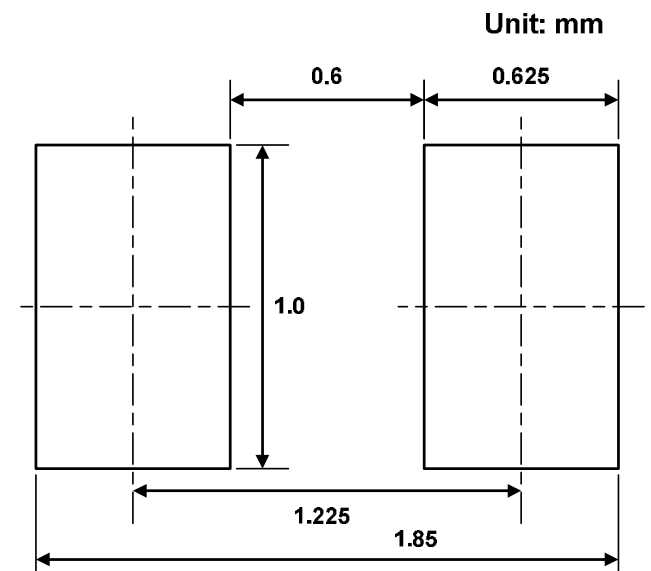
Notes:

This LAND LAYOUT is for reference purposes only. Please consult your manufacturing partners to ensure your company's PCB design guidelines are met.

MARKING CODE

Top View

Z = Device Code
X = Date Code

Part Number	Marking Code
AZ9720-01F.R7G (Green Part)	ZX

Note. Green means Pb-free, RoHS, and Halogen free compliant.

Ordering Information

PN#	Material	Type	Reel size	MOQ	MOQ/internal box	MOQ/carton
AZ9720-01F.R7G	Green	T/R	7 inch	3,000/reel	4 reels= 12,000/box	6 boxes =72,000/carton

Revision History

Revision	Modification Description
Revision 2017/03/07	Formal Release.